





CIES

Technology

CIES Progress Report March 25, 2019

Otemachi Sankei Plaza 4F 1-7-2 Otemachi, Chiyoda-ku, Tokyo 100-0004, Japan

Welcome address Hideo Ohno (Tohoku Univ.)

Address Akira Sudo (CAO)

Hiroki Matsuo (MEXT) Shoji Watanabe (METI) Takashi Yamashita (JPO)

CIES overview Tetsuo Endoh (Tohoku Univ.)

Progress report Tetsuo Endoh (Tohoku Univ.)

Masanori Hariyama (Tohoku Univ.)

Koichi Ito (Tohoku Univ.) Yasuo Ando (Tohoku Univ.) Masaaki Niwa (Tohoku Univ.)

Yasunobu Mizomoto (Tohoku Univ.)

Closing remarks Tetsuo Endoh (Tohoku Univ.)

Sponsors CAO, MEXT, METI, JPO,

JSPS, JST, NEDO, INPIT

# Forum

March 24 - 26, 2019

DAY 2

#### Registration

www.cies.tohoku.ac.jp/ 5th\_forum/entry.html

Registration fee: Free Pre-registration deadline: March 20, 2019

#### Tohoku University Center for Innovative Integrated Electronic Systems

468-1 Aramaki Aza Aoba, Aoba-ku, Sendai, Miyagi, 980-8572, JAPAN TEL +81-22-796-3410 FAX +81-22-796-3432 support-office@cies.tohoku.ac.jp

www.cies.tohoku.ac.jp



## 5th CIES **Technology Forum**

March 25, 2019

Otemachi Sankei Plaza 4F



The Sustainable Growth in Physical Space with Innovative Integrated Electronic Technologies From ultra low power edge computing and car electronics to AI systems



<<< Registration desk open at 9:15am>>>

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10:00-10:30	Welcome address President, Tohoku Univ.	Hideo Ohno (Tohoku Univ.)
	Address CAO	Akira Sudo (CAO)
	Address Director-General, Science and Technology Policy Bureau, MEXT	Hiroki Matsuo (MEXT)
	Address Deputy Director-General, Industrial Science and Technology Policy and Environment Bureau, METI	Shoji Watanabe (METI)
	Address Director-General, 4th Patent Examination Department, JPO	Takashi Yamashita (JPO)
10:30-11:10	CIES Overview	Tetsuo Endoh (Tohoku Univ.)
11:10-11:50	Industry-academic collaboration STT-MRAM aimed at developing non-volatile working memory and its manufacturing technologies	Tetsuo Endoh (Tohoku Univ.)
11:50-13:20	Lunch	
13:20-13:50	Industry-academic collaboration  Development of a Low-Power and High-Performance Edge AI Processor	Masanori Hariyama (Tohoku Univ.)
13:50-14:20	Industry-academic collaboration Embedded security technology	Koichi Ito (Tohoku Univ.)
14:20-14:50	Industry-academic collaboration Supersensitive magnetic sensors using ferromagnetic tunnel junctions	Yasuo Ando (Tohoku Univ.)
14:50-15:10	Break	
15:10-15:40	JSPS Core-to-Core (Japan – UK – France) Creation of international research hub for innovative semiconductor materials and devices	Masaaki Niwa (Tohoku Univ.)
15:40-16:00	JST ACCEL  Three-dimensional integrated circuits technology based on vertical BC-MOSFET and its advanced application exploration	Tetsuo Endoh (Tohoku Univ.)
16:00-16:40	CAO ImPACT Ohno implementation branch: Spintronics integrated circuit project	Tetsuo Endoh (Tohoku Univ.)
16:40-17:00	JST OPERA World-leading open innovation platform of fusion technologies bridged IT and transportation system areas	Tetsuo Endoh (Tohoku Univ.)
17:00-17:20	Community-based cooperation project Progress and prospect of CIES's Community-based cooperation project	Yasunobu Mizomoto (Tohoku Univ.)
17:20-17:40	CAO SIP R&D of ultra low power IoT devices and its technology platform with MTJ/CMOS hybrid technology for Society 5.0	Tetsuo Endoh (Tohoku Univ.)
17:40-17:50	Closing remarks	Tetsuo Endoh (Tohoku Univ.)

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